

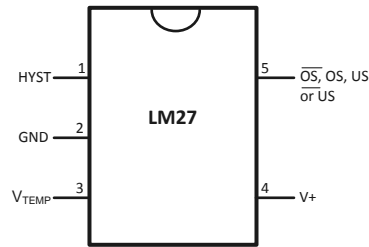


**Table 1. Summary Table of Trip Point and Output Function Capabilities of Released Parts<sup>(1)</sup>**

Orderable Device	Trip Point Temperature (°C)	Digital Output Function
LM27CIM5-ZHJ	120	Active-Low, Open-Drain, $\overline{OS}$ output
LM27CIM5-1HJ	130	Active-Low, Open-Drain, $\overline{OS}$ output
LM27CIM5-2HJ	140	Active-Low, Open-Drain, $\overline{OS}$ output

(1) Other device options have not been released to market, contact Texas Instruments for volume and other requirements for release.

## Connection Diagram



## PIN DESCRIPTIONS

Pin Number	Pin Name	Function	Connection
1	HYST	Hysteresis control, digital input	GND for 10°C or V <sup>+</sup> for 2°C
2	GND	Ground, connected to the back side of the die through lead frame.	System GND
3	V <sub>TEMP</sub>	Analog output voltage proportional to temperature	Leave floating or connect to a high impedance node.
4	V <sup>+</sup>	Supply input	2.7V to 5.5V with a 0.1μF bypass capacitor. For PSRR information see <a href="#">NOISE CONSIDERATIONS</a> .
5 <sup>(1)</sup>	$\overline{OS}$	Overtemperature Shutdown open-drain active low thermostat digital output	Controller interrupt, system or power supply shutdown; pull-up resistor ≥ 10kΩ
	OS	Overtemperature Shutdown totem-pull active high thermostat digital output	Controller interrupt, system or power supply shutdown
	$\overline{US}$	Undertemperature Shutdown open-drain active low thermostat digital output	System or power supply shutdown; pull-up resistor ≥ 10kΩ
	US	Undertemperature Shutdown totem-pull active high thermostat digital output	System or power supply shutdown

(1) Pin 5 functionality and trip point setting are programmed during LM27 manufacture.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

**Absolute Maximum Ratings<sup>(1)</sup>**

Input Voltage		6.0V	
Input Current at any pin <sup>(2)</sup>		5mA	
Package Input Current <sup>(2)</sup>		20mA	
Package Dissipation at T <sub>A</sub> = 25°C <sup>(3)</sup>		500mW	
Soldering Information <sup>(4)</sup>	SOT23 Package	Vapor Phase (60 seconds)	215°C
		Infrared (15 seconds)	220°C
Storage Temperature		-65°C to + 150°C	
ESD Susceptibility <sup>(5)</sup>	Human Body Model	2500V	
	Machine Model	250V	

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics. The specified specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.
- (2) When the input voltage (V<sub>I</sub>) at any pin exceeds the power supply (V<sub>I</sub> < GND or V<sub>I</sub> > V<sup>+</sup>), the current at that pin should be limited to 5mA. The 20mA maximum package input current rating limits the number of pins that can safely exceed the power supplies with an input current of 5mA to four. Under normal operating conditions the maximum current that pins 2, 4 or 5 can handle is limited to 5mA each.
- (3) The maximum power dissipation must be derated at elevated temperatures and is dictated by T<sub>Jmax</sub> (maximum junction temperature), θ<sub>JA</sub> (junction to ambient thermal resistance) and T<sub>A</sub> (ambient temperature). The maximum allowable power dissipation at any temperature is P<sub>D</sub> = (T<sub>Jmax</sub> - T<sub>A</sub>) / θ<sub>JA</sub> or the number given in the Absolute Maximum Ratings, whichever is lower. For this device, T<sub>Jmax</sub> = 150°C. For this device the typical thermal resistance (θ<sub>JA</sub>) of the different package types when board mounted refer to [Table 2](#)
- (4) See <http://www.ti.com/packaging> for other recommendations and methods of soldering surface mount devices.
- (5) The human body model is a 100pF capacitor discharge through a 1.5kΩ resistor into each pin. The machine model is a 200pF capacitor discharged directly into each pin.

**Table 2.**

Package Type	θ <sub>JA</sub>
SOT23-5, DBV	250°C/W

**Operating Ratings<sup>(1)</sup>**

Specified Temperature Range	T <sub>MIN</sub> ≤ T <sub>A</sub> ≤ T <sub>MAX</sub>
LM27CIM	-40°C ≤ T <sub>A</sub> ≤ +150°C
Positive Supply Voltage (V <sup>+</sup> )	+2.7V to +5.5V
Maximum V <sub>OUT</sub>	+5.5V

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits. For ensured specifications and test conditions, see the Electrical Characteristics. The specified specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

## LM27 Electrical Characteristics

The following specifications apply for  $V^+ = 2.7V_{DC}$  to  $5.5V_{DC}$ , and  $V_{TEMP}$  load current =  $0\mu A$  unless otherwise specified.

**Boldface limits apply for  $T_A = T_J = T_{MIN}$  to  $T_{MAX}$** ; all other limits  $T_A = T_J = 25^\circ C$  unless otherwise specified.

Symbol	Parameter	Conditions	Typical <sup>(1)</sup>	LM27CIM Limits <sup>(2)</sup>	Units (Limits)
<b>Temperature Sensor</b>					
	Trip Point Accuracy (Includes $V_{REF}$ , DAC, Comparator Offset, and Temperature Sensitivity errors)	$+120^\circ C < T_A < +150^\circ C$		$\pm 3$	$^\circ C$ (max)
	Trip Point Hysteresis	HYST = GND	10		$^\circ C$
		HYST = $V^+$	2		$^\circ C$
	$V_{TEMP}$ Output Temperature Sensitivity		-10.82		mV/ $^\circ C$
	$V_{TEMP}$ Temperature Sensitivity Error to Equation: $V_O = (-3.552 \times 10^{-6} \times (T-30))^2 + (-10.695 \times 10^{-3} \times (T-30)) + 1.8386V$ (1)	$-30^\circ C \leq T_A \leq 150^\circ C$ , $2.7V \leq V^+ \leq 5.5V$		$\pm 3$	$^\circ C$ (max)
		$-55^\circ C \leq T_A \leq 150^\circ C$ , $4.5V \leq V^+ \leq 5.5V$		$\pm 3$	$^\circ C$ (max)
		$T_A = 25^\circ C$			$\pm 2.5$
	$V_{TEMP}$ Load Regulation	Source $\leq 1 \mu A$	0.070		mV
		Sink $\leq 40 \mu A$			<b>0.7</b>
	$V_{TEMP}$ Line Regulation	$+2.7V \leq V^+ \leq +5.5V$ , $-30^\circ C \leq T_A \leq +120^\circ C$	-0.2		mV/V
$I_S$	Supply Current		15	22 <b>40</b>	$\mu A$ (max) $\mu A$ (max)
<b>Digital Output and Input</b>					
$I_{OUT("1")}$	Logical "1" Output Leakage Current <sup>(3)</sup>	$V^+ = +5.0V$	0.001	<b>1</b>	$\mu A$ (max)
$V_{OUT("0")}$	Logical "0" Output Voltage	$I_{OUT} = +1.2mA$ and $V^+ \geq 2.7V$ ; $I_{OUT} = +3.2mA$ and $V^+ \geq 4.5V$ <sup>(4)</sup>		<b>0.4</b>	V (max)
$V_{OUT("1")}$	Logical "1" Push-Pull Output Voltage	$I_{SOURCE} = 500\mu A$ , $V^+ \geq 2.7V$		<b><math>0.8 \times V^+</math></b>	V (min)
		$I_{SOURCE} = 800\mu A$ , $V^+ \geq 4.5V$		<b><math>V^+ - 1.5</math></b>	V (min)
$V_{IH}$	HYST Input Logical "1" Threshold Voltage			<b><math>0.8 \times V^+</math></b>	V (min)
$V_{IL}$	HYST Input Logical "0" Threshold Voltage			<b><math>0.2 \times V^+</math></b>	V (max)

(1) Typicals are at  $T_J = T_A = 25^\circ C$  and represent most likely parametric norm.

(2) Limits are ensured to AOQL (Average Outgoing Quality Level).

(3) The  $1\mu A$  limit is based on a testing limitation and does not reflect the actual performance of the part. Expect to see a doubling of the current for every  $15^\circ C$  increase in temperature. For example, the  $1nA$  typical current at  $25^\circ C$  would increase to  $16nA$  at  $85^\circ C$ .

(4) Care should be taken to include the effects of self heating when setting the maximum output load current. The power dissipation of the LM27 would increase by  $1.28mW$  when  $I_{OUT}=3.2mA$  and  $V_{OUT}=0.4V$ . With a thermal resistance of  $250^\circ C/W$ , this power dissipation would cause an increase in the die temperature of about  $0.32^\circ C$  due to self heating. Self heating is not included in the trip point accuracy specification.

## Part Number Template

The series of digits labeled xyz in the part number LM27CIM-xyz, describe the set point value and the function of the output as follows:

The place holders xy describe the set point temperature as shown in the following table.

x (10x)	y (1x)	Temperature (°C)
-	H	0
-	J	1
-	K	2
-	L	3
-	N	4
-	P	5
-	R	6
-	S	7
-	T	8
-	V	9
Z	-	12
1	-	13
2	-	14
3	-	15

The value of z describes the assignment/function of the output as shown in the following table:

Active-Low/High	Open-Drain/ Push-Pull	$\overline{OS}/US$	Value of z	Digital Output Function
0	0	0	J	Active-Low, Open-Drain, $\overline{OS}$ output
0	0	1	K	Active-Low, Open-Drain, $\overline{US}$ output
1	1	0	L	Active-High, Push-Pull, OS output
1	1	1	N	Active-High, Push-Pull, US output

For example:

- the part number LM27CIM5-2SJ has  $T_{OS} = 147^{\circ}\text{C}$ , and programmed as an active-low open-drain overtemperature shutdown output.
- the part number LM27CIM5-ZLN has  $T_{US} = 123^{\circ}\text{C}$ , and programmed as an active-high, push-pull undertemperature shutdown output.

Active-high open-drain and active-low push-pull options are available, please contact Texas Instruments for more information.

**Note:** Currently, there are several standard parts available, see [Table 1](#). For other part options, contact a Texas Instruments Distributor or Sales Representative for information on minimum order qualification

## FUNCTIONAL DESCRIPTION

### LM27 OPTIONS — Output Pin Options Block Diagrams

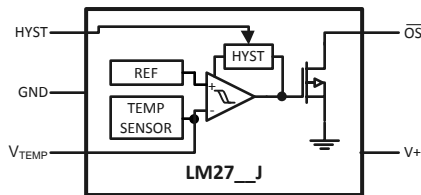


Figure 1. LM27-\_\_J

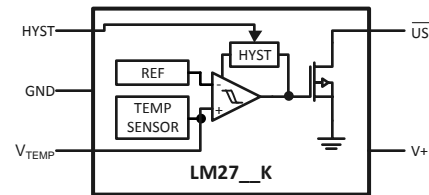


Figure 2. LM27-\_\_K

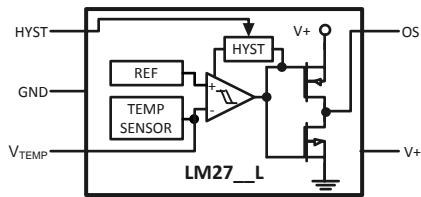


Figure 3. LM27-\_\_L

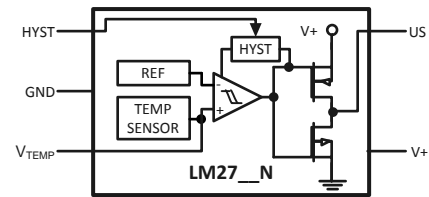


Figure 4. LM27-\_\_N

The LM27 can be factory programmed to have a trip point anywhere in-between 120°C to 150°C.

### Applications Hints

#### AFTER-ASSEMBLY PCB TESTING

The LM27's  $V_{TEMP}$  output allows after-assembly PCB testing by following a simple test procedure. Simply measuring the  $V_{TEMP}$  output voltage will verify that the LM27 has been assembled properly and that its temperature sensing circuitry is functional. The  $V_{TEMP}$  output has very weak drive capability that can be overdriven by 1.5mA. Therefore, one can simply force the  $V_{TEMP}$  voltage to cause the digital output to change state, thereby verifying that the comparator and output circuitry function after assembly. Here is a sample test procedure that can be used to test the LM27CIM5X-2HJ which has a 140°C trip point.

1. Turn on  $V^+$  and measure  $V_{TEMP}$ . Then calculate the temperature reading of the LM27 using the equation:

$$V_O = (-3.552 \times 10^{-6} \times (T-30)^2) + (-10.69576 \times 10^{-3} \times (T-30)) + 1.8386V \quad (2)$$

or

$$T = -1475.49 + \sqrt{2.2668 \times 10^6 + \frac{1.8386 - V_{TEMP}}{3.552 \times 10^{-6}}} \quad (3)$$

2. Verify that the temperature measured in step one is within ( $\pm 3^\circ\text{C}$  + error of reference temperature sensor) of the ambient/board temperature. The ambient/board temperature (reference temperature) should be measured using an extremely accurate calibrated temperature sensor, which is in close proximity to and mounted on the same PCB as the LM27 perhaps even touching the GND lead of the LM27 if possible. The LM27 will sense the board temperature not the ambient temperature (see [MOUNTING CONSIDERATIONS](#))
3.
  - (a) Observe that  $\overline{OS}$  is high.
  - (b) Drive  $V_{TEMP}$  to ground.
  - (c) Observe that  $\overline{OS}$  is now low.
  - (d) Release the  $V_{TEMP}$  pin.
  - (e) Observe that  $\overline{OS}$  is now high.
4.
  - (a) Observe that  $\overline{OS}$  is high.
  - (b) Drive  $V_{TEMP}$  voltage down gradually.
  - (c) When  $\overline{OS}$  goes low, note the  $V_{TEMP}$  voltage.
  - (d)  $V_{TEMP}^{Trig} = V_{TEMP}$  at  $\overline{OS}$  trigger (HIGH->LOW)
  - (e) Calculate  $T_{trig}$  using [Equation 3](#).

5.
  - (a) Gradually raise  $V_{TEMP}$  until OS goes HIGH. Note  $V_{TEMP}$ .
  - (b) Calculate  $T_{HYST}$  using Equation 3.

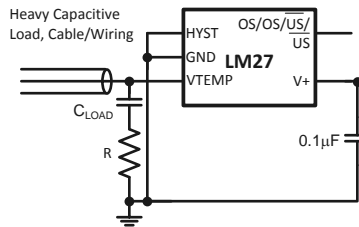
### $V_{TEMP}$ LOADING

The  $V_{TEMP}$  output has very weak drive capability (1  $\mu$ A source, 40  $\mu$ A sink). So care should be taken when attaching circuitry to this pin. Capacitive loading may cause the  $V_{TEMP}$  output to oscillate. Simply adding a resistor in series as shown in Figure 6 will prevent oscillations from occurring. To determine the value of the resistor follow the guidelines given in Table 3. The same value resistor will work for either placement of the resistor. If an additional capacitive load is placed directly on the LM27 output, rather than across  $C_{LOAD}$ , it should be at least a factor of 10 smaller than  $C_{LOAD}$ .

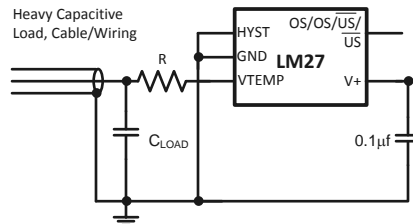
**Table 3. Resistive compensation for capacitive loading of  $V_{TEMP}$**

$C_{LOAD}$	R ( $\Omega$ )
$\leq 100$ pF	0
1nF	8200
10nF	3000
100nF	1000
$\geq 1$ $\mu$ F	430

### Resistor placement for capacitive loading compensation of $V_{TEMP}$



**Figure 5. R in series with capacitor**



**Figure 6. R in series with signal path**

### NOISE CONSIDERATIONS

The LM27 has excellent power supply noise rejection. Listed below is a variety of signals used to test the LM27 power supply rejection. False triggering of the output was not observed when these signals were coupled into the V+ pin of the LM27.

- square wave 400kHz, 1Vp-p
- square wave 2kHz, 200mVp-p
- sine wave 100Hz to 1MHz, 200mVp-p

Testing was done while maintaining the temperature of the LM27 one degree centigrade away from the trip point with the output not activated.

## MOUNTING CONSIDERATIONS

The LM27 can be applied easily in the same way as other integrated-circuit temperature sensors. It can be glued or cemented to a surface. The temperature that the LM27 is sensing will be within about  $+0.06^{\circ}\text{C}$  of the surface temperature to which the LM27's leads are attached to.

This presumes that the ambient air temperature is almost the same as the surface temperature; if the air temperature were much higher or lower than the surface temperature, the actual temperature measured would be at an intermediate temperature between the surface temperature and the air temperature.

To ensure good thermal conductivity, the backside of the LM27 die is directly attached to the GND pin (pin 2). The temperatures of the lands and traces to the other leads of the LM27 will also affect the temperature that is being sensed.

Alternatively, the LM27 can be mounted inside a sealed-end metal tube, and can then be dipped into a bath or screwed into a threaded hole in a tank. As with any IC, the LM27 and accompanying wiring and circuits must be kept insulated and dry, to avoid leakage and corrosion. This is especially true if the circuit may operate at cold temperatures where condensation can occur. Printed-circuit coatings and varnishes such as Humiseal and epoxy paints or dips are often used to ensure that moisture cannot corrode the LM27 or its connections.

The junction to ambient thermal resistance ( $\theta_{JA}$ ) is the parameter used to calculate the rise of a part's junction temperature due to its power dissipation. For the LM27 the equation used to calculate the rise in the die junction temperature is as follows:

$$T_J = T_A + \theta_{JA}(V^+I_Q + (V^+ - V_{TEMP})I_{L\_TEMP} + V_{DO}I_{DO}) \quad (4)$$

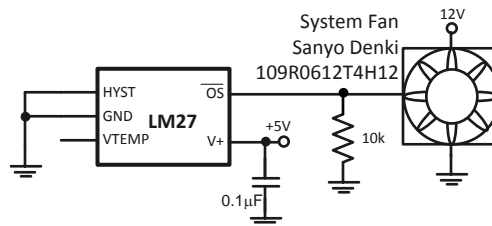
where  $T_A$  is the ambient temperature,  $V^+$  is the power supply voltage,  $I_Q$  is the quiescent current,  $I_{L\_TEMP}$  is the load current on the  $V_{TEMP}$  output,  $V_{DO}$  is the voltage on the digital output, and  $I_{DO}$  is the load current on the digital output. Since the LM27's junction temperature is the actual temperature being measured, care should be taken to minimize the load current that the LM27 is required to drive.

The tables shown in [Table 4](#) summarize the thermal resistance for different conditions and the rise in die temperature of the LM27 without any loading on  $V_{TEMP}$  and a 10k pull-up resistor on an open-drain digital output with a 5.5V power supply.

**Table 4. Thermal resistance ( $\theta_{JA}$ ) and temperature rise due to self heating ( $T_J - T_A$ )**

	SOT23-5 no heat sink		SOT23-5 small heat sink	
	$\theta_{JA}$ ( $^{\circ}\text{C}/\text{W}$ )	$T_J - T_A$ ( $^{\circ}\text{C}$ )	$\theta_{JA}$ ( $^{\circ}\text{C}/\text{W}$ )	$T_J - T_A$ ( $^{\circ}\text{C}$ )
Still Air	250	0.11	TBD	TBD
Moving Air	TBD	TBD	TBD	TBD

## Typical Applications



The fan's control pin has internal pull-up. The 10k pull-down sets a slow fan speed. When the output of the LM27 goes low, the fan will speed up.

**Figure 7. Two Speed Fan Speed Control**



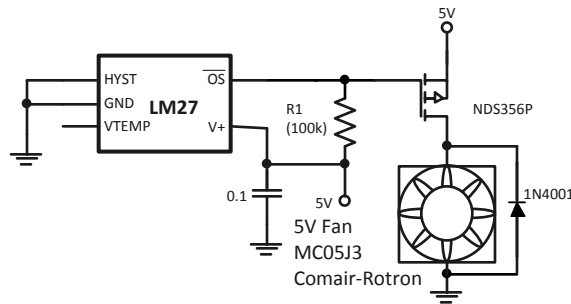


Figure 8. Fan High Side Drive

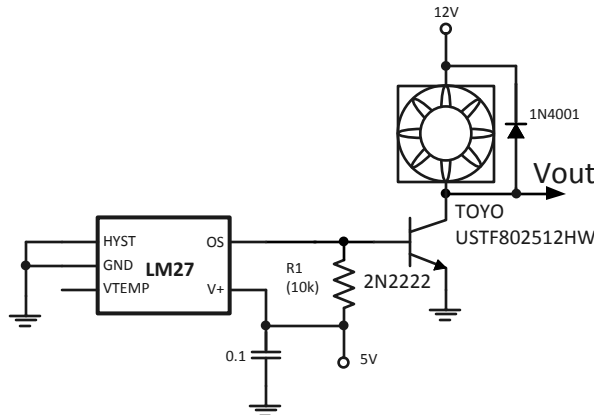


Figure 9. Fan Low Side Drive

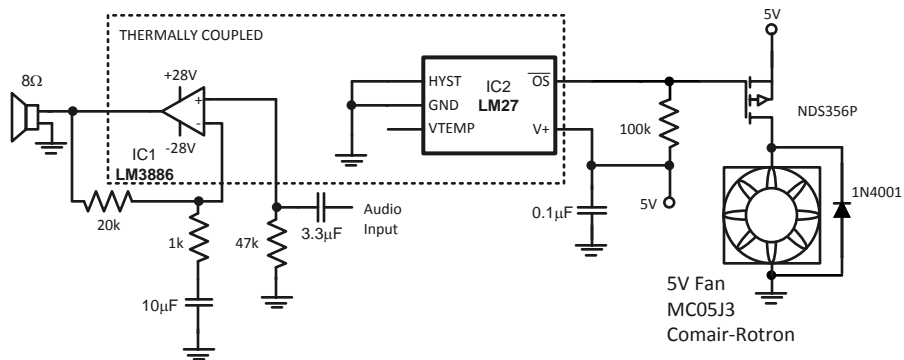


Figure 10. Audio Power Amplifier Thermal Protection

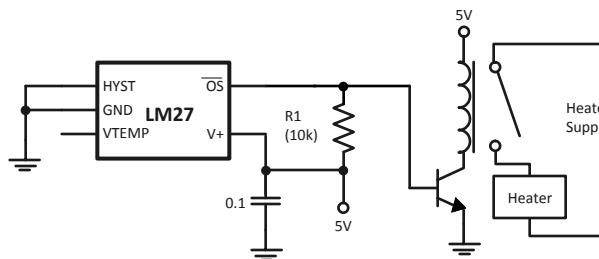


Figure 11. Simple Thermostat

## REVISION HISTORY

Changes from Revision B (March 2013) to Revision C	Page
• Deleted layout of National Data Sheet to TI format .....	<a href="#">9</a>

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM27CIM5-1HJ/NOPB	ACTIVE	SOT-23	DBV	5	1000	RoHS & Green	SN	Level-1-260C-UNLIM	120 to 150	T1HJ	<a href="#">Samples</a>
LM27CIM5-2HJ/NOPB	ACTIVE	SOT-23	DBV	5	1000	RoHS & Green	SN	Level-1-260C-UNLIM	120 to 150	T2HJ	<a href="#">Samples</a>
LM27CIM5-ZHJ/NOPB	ACTIVE	SOT-23	DBV	5	1000	RoHS & Green	SN	Level-1-260C-UNLIM	120 to 150	TZHJ	<a href="#">Samples</a>
LM27CIM5X-1HJ/NOPB	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	SN	Level-1-260C-UNLIM		T1HJ	<a href="#">Samples</a>
LM27CIM5X-2HJ/NOPB	ACTIVE	SOT-23	DBV	5	3000	RoHS & Green	SN	Level-1-260C-UNLIM		T2HJ	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM27CIM5-1HJ/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LM27CIM5-2HJ/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LM27CIM5-ZHJ/NOPB	SOT-23	DBV	5	1000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LM27CIM5X-1HJ/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
LM27CIM5X-2HJ/NOPB	SOT-23	DBV	5	3000	178.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM27CIM5-1HJ/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LM27CIM5-2HJ/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LM27CIM5-ZHJ/NOPB	SOT-23	DBV	5	1000	210.0	185.0	35.0
LM27CIM5X-1HJ/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0
LM27CIM5X-2HJ/NOPB	SOT-23	DBV	5	3000	210.0	185.0	35.0

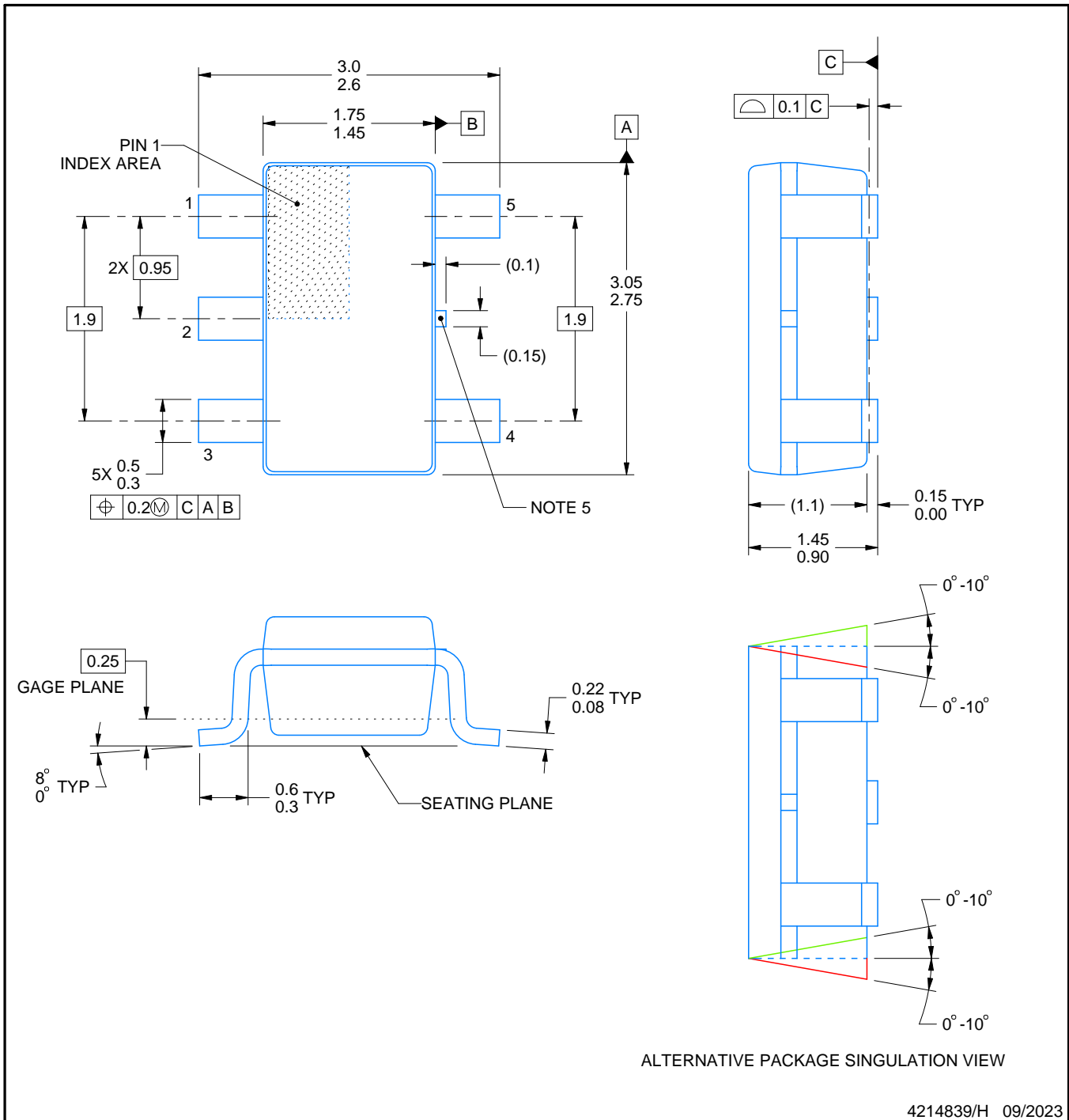
# DBV0005A



# PACKAGE OUTLINE

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC MO-178.
4. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25 mm per side.
5. Support pin may differ or may not be present.

# EXAMPLE BOARD LAYOUT

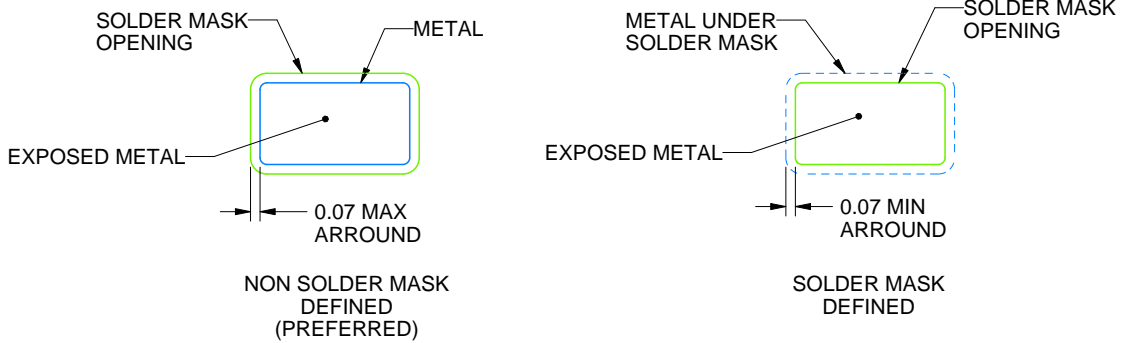
DBV0005A

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LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS

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NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# EXAMPLE STENCIL DESIGN

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SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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